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02/15/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10075226	02/15/2002	174	52.4	2831	OL+VA N80

**APPLICANTS: Ou In-De; Ding Yi-Chuan; Chen Kun-Ching;

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☒ no

35 USC 119 conditions met ☐ yes ☒ no

Verified and Acknowledged Examiners's initials HVN

ATTORNEY DOCKET NO

BHT-3183-39

TITLE : Thermally enhanced semiconductor build-up package

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

CLAIMS ALLOWED

Assistant Examiner

Total Claims

Print Claim for
O.G.

ISSUE FEE

Amount Due

Date Paid

Sheets Drwg.

Figs Drwg.

Print Fig.

Primary Examiner

PREPARED FOR ISSUE

Application Examiner



TERMINAL

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